CLAIMS
We claim,

1. A low surface tension, low viscosity, aqueous composition, consisting essentially of an admixture of;

   a. an acidic buffer solution,
   b. a polar, organic solvent that is miscible in all proportions in water,
   c. a fluoride, and
   d. water,

   where the aqueous composition has a pH of from about 3 to about 6 and is free of glycols.

2. The composition as claimed in claim 1, further consisting essentially of a corrosion inhibitor.

3. The composition as claimed in claim 1, wherein the acidic buffer solution contains an ammonium salt of a carboxylic acid or a polybasic acid.

4. The composition as claimed in claim 1, wherein the polar solvent is , monoethanolamine, n-methylethanolamine, formamide, n-methylformamide, dimethylacetamide, gamma-butyrolactone, N-methylpyrrolidone or mixtures thereof.

5. The composition as claimed in claim 1, where the fluoride has a composition of the general formula R_1,R_2,R_3,R_4NF, where R_1,R_2,R_3 and R_4 are independently hydrogen, an alcohol group, an alkoxy group, an alkyl group and mixtures thereof.

6. The composition as claimed in claim 2, wherein the corrosion inhibitor has a pKa of less than about 6.

7. The composition as claimed in claim 2, wherein the corrosion inhibitor is anthranilic acid, gallic acid, benzoic acid,malonic acid, maleic acid, fumaric acid, D,L-malic acid, isophthalic acid, phthalic acid, maleic anhydride, phthalic anhydride or mixtures thereof.

8. The composition as claimed in 3, wherein the acidic buffer is a solution of ammonium acetate and acetic acid.

9. The composition as claimed in claim 1, where the fluoride is flouroboric acid.

10. The composition as claimed in claim 5, where the fluoride is ammonium fluoride, tetramethyl ammonium fluoride, or tetraethyl ammonium fluoride.

11. The composition as claimed in claim 1 having a surface tension less than or equal to 30 mN/m and a viscosity of less than or equal to 15 centipoise at 25°C.

12. A low surface tension, low viscosity, composition, consisting essentially of;

a. an acidic buffer solution containing acetic acid and ammonium acetate,
b. from 30% by weight to 90% by weight of an organic polar solvent that is miscible in all proportion in water,
c. from 0.1% by weight to 20% by weight of ammonium fluoride, and
d. from 0.5% by weight to 40% by weight of water, and
f. up to 15% by weight of a corrosion inhibitor

wherein the pH of the composition is between 3 and 6 and the composition is free of glycols.

13. A low surface tension, low viscosity, aqueous composition, consisting essentially of an admixture of;

a. ammonium acetate;
b. dimethylacetamide,
c. acetic acid,
d. a 40% aqueous ammonium fluoride solution, and
e. deionized water,

where the pH of the admixture is from about 3 to about 6 and the composition is free of glycols.

14. A method of removing photoresist or residue from a substrate, comprising; applying a composition according to claim 1 to the substrate at a temperature of from 20°C to 80°C for a period of time sufficient to remove the coating from the substrate.

15. The method as claimed in claim 14, wherein the temperature is from 20°C to 60°C.
16. The method as claimed in claim 14, where the temperature is from 20°C to about 40°C
17. The method as claimed in claim 14, where the temperature is 20°C.